



## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752</b> Distribute	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2014-01-22</b>
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	<b>Giuseppe Vitali Palma</b>	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.


**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
------------------------------	-------------	----------------------------	-----------------

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	FYND*UI73ACA	A	Z6HA	2014-01-22
Amount	UoM	Unit type	ST ECOPACK Grade	
44.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	4X4X1.0	25	No lead	
Comment	Package: VFQFPN 4x4x1.0 24 PITCH 0.5			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	<b>false</b>
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	<b>false</b>
Product(s) does not meet EU RoHS requirements and is not under exemptions	<b>false</b>
Product(s) is obsolete, no information is available	<b>false</b>
Product(s) is unknown, no information is available	<b>false</b>
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	FYND*UI73ACA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	2.546	mg	SUPPLIER	Die	Si	7440-21-3		2.432	mg	955224	55273
Silicon die			mg	SUPPLIER	Metallization	Aluminium (Al)	7429-90-5		0.025	mg	9819	568
Silicon die			mg	SUPPLIER	Metallization	Titanium (Ti)	7440-32-6		0.001	mg	393	23
Silicon die			mg	SUPPLIER	Metallization	Tungsten (W)	7440-33-7		0.02	mg	7855	455
Silicon die			mg	SUPPLIER	Passivation	Silicon Nitride (SiN)	68034-42-4		0.005	mg	1964	114
Silicon die			mg	SUPPLIER	Passivation	Silicon Oxide(SiO2)	7631-86-9		0.043	mg	16889	977
Silicon die			mg	SUPPLIER	Passivation	Gamma-butyrolactone	96-48-0		0.014	mg	5499	318
Silicon die			mg	SUPPLIER	Passivation	Polyhydroxyamide	55295-98-2		0.006	mg	2357	136
Leadframe	Copper and its alloy	16.817	mg	SUPPLIER	Alloy	Copper	7440-50-8		16.241	mg	965749	369114
Leadframe			mg	SUPPLIER	Alloy	Iron	7439-89-6		0.382	mg	22715	8682
Leadframe			mg	SUPPLIER	Alloy	Phosphorus	7723-14-0		0.004	mg	238	91
Leadframe			mg	SUPPLIER	Alloy	Zinc	7440-66-6		0.021	mg	1249	477
Leadframe			mg	SUPPLIER	Alloy	Silver	7440-22-4		0.169	mg	10049	3841
Die Attach	Other organic materials	0.191	mg	SUPPLIER	Epoxy	Silver	7440-22-4		0.153	mg	801047	3477
Die Attach			mg	SUPPLIER	Epoxy	methylene diacrylate	42594-17-2		0.019	mg	99476	432
Die Attach			mg	SUPPLIER	Epoxy	Dicyclopentenyl ether methyl methacrylate	68586-19-6		0.006	mg	31414	136
Die Attach			mg	SUPPLIER	Epoxy	Polymer of Polybutadiene + Anhydride	Proprietary		0.006	mg	31414	136
Die Attach			mg	SUPPLIER	Epoxy	Palladium (Pd)	7440-05-3		0.006	mg	31414	136
Bonding wire	Other inorganic materials	0.306	mg	SUPPLIER	Epoxy	Dicumyl peroxide	80-43-3		0.001	mg	5236	23
Encapsulation	Other organic materials	23.06	mg	SUPPLIER	Bonding Wire	Au	7440-57-5		0.306	mg	1000000	6955
Encapsulation			mg	SUPPLIER	molding compound	Silica Fused	60676-86-0		21.606	mg	936947	491045
Encapsulation			mg	SUPPLIER	molding compound	Epoxy Resin	Proprietary		0.692	mg	30009	15727
Encapsulation			mg	SUPPLIER	molding compound	Phenol Resin	Proprietary		0.692	mg	30009	15727
Encapsulation			mg	SUPPLIER	molding compound	Carbon Black	1333-86-4		0.07	mg	3036	1591
Finishing	Other organic materials	1.08	mg	SUPPLIER	Connection coating	Sn	7440-31-5		1.08	mg	1000000	24545